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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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100V PNP MEDIUM POWER TRANSISTOR IN SOT89

Features

- $BV_{CEO} > -100V$
- $I_C = -1A$ high Continuous Collector Current
- $I_{CM} = -2A$ Peak Collector Current
- Low saturation voltage $V_{CE(sat)} < -200mV @ -250mA$
- Complementary NPN type: FCX493
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

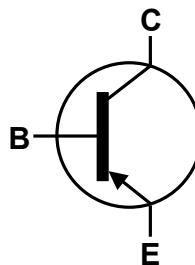
Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic. "Green" Molding Compound
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per
MIL-STD-202, Method 208^③
- Weight: 0.05 grams (Approximate)

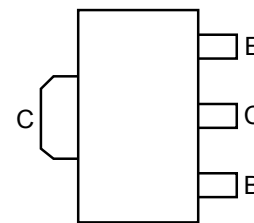
SOT89



Top View



Device Symbol



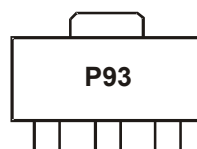
Top View
Pin Out

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FCX593TA	P93	7	12	1,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



P93 = Product Type Marking Code

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Limit	Unit
Collector-Base Voltage	V _{CB0}	-120	V
Collector-Emitter Voltage	V _{CEO}	-100	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-1	A
Peak Pulse Current	I _{CM}	-2	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

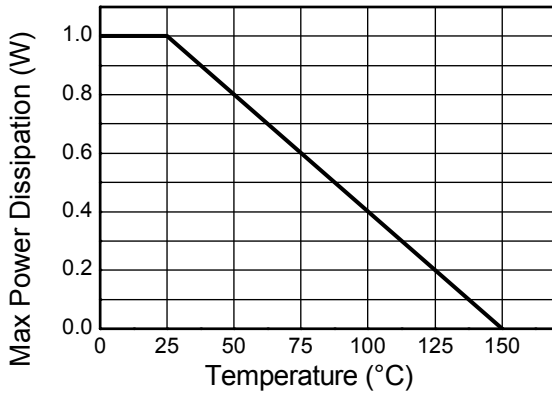
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	(Note 5)	1
		(Note 6)	1.5
		(Note 7)	2.0
Thermal Resistance, Junction to Ambient Air	R _{θJA}	(Note 5)	125
		(Note 6)	83
		(Note 7)	60
Thermal Resistance, Junction to Lead	R _{θJL}	22	°C/W
Thermal Resistance, Junction to Case	R _{θJC}	16	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 10)

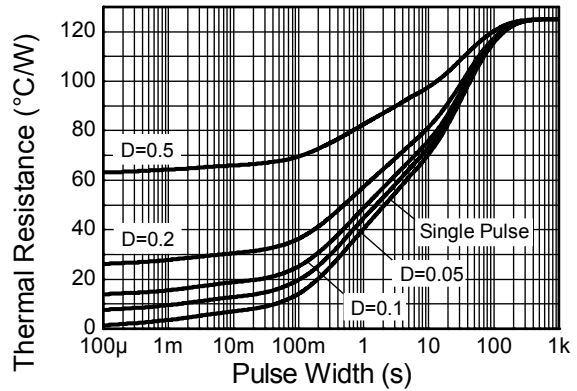
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Same as note (5), except the device is mounted on 25mm x 25mm 1oz copper.
 - Same as note (5), except the device is mounted on 50mm x 50mm 1oz copper.
 - Thermal resistance from junction to solder-point (on the exposed collector pad).
 - Thermal resistance from junction to the top of the case.
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

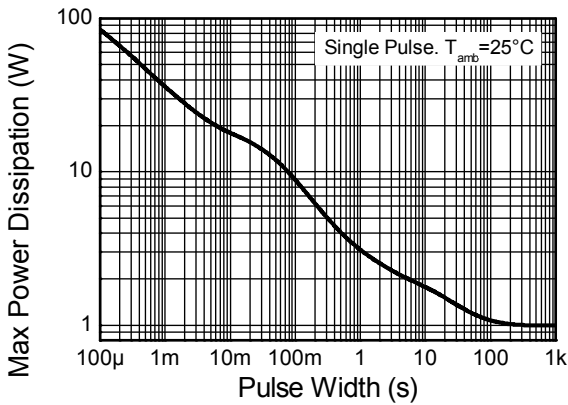
Thermal Characteristics and Derating Information



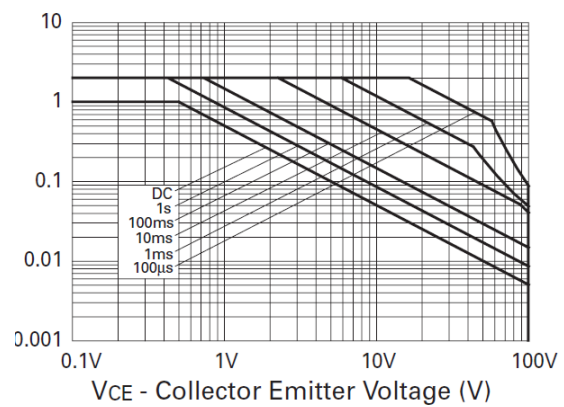
Derating Curve



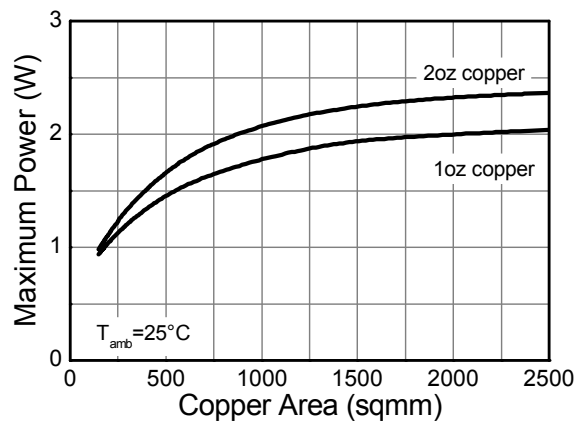
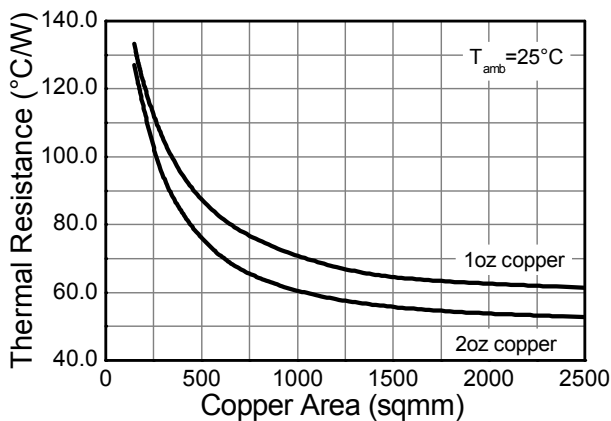
Transient Thermal Impedance



Pulse Power Dissipation



Safe Operating Area

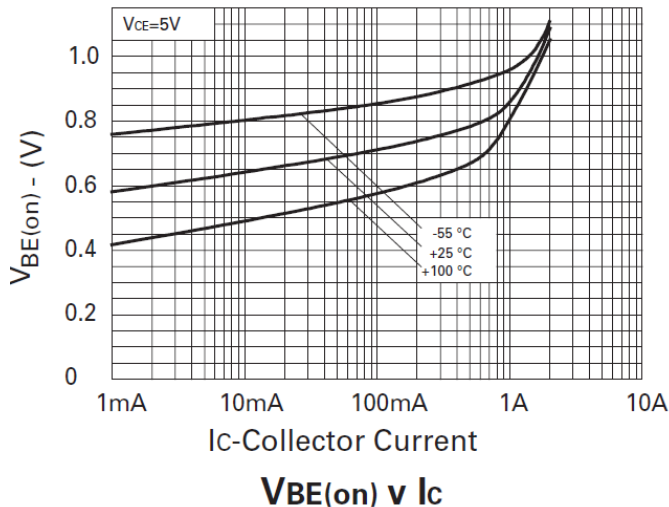
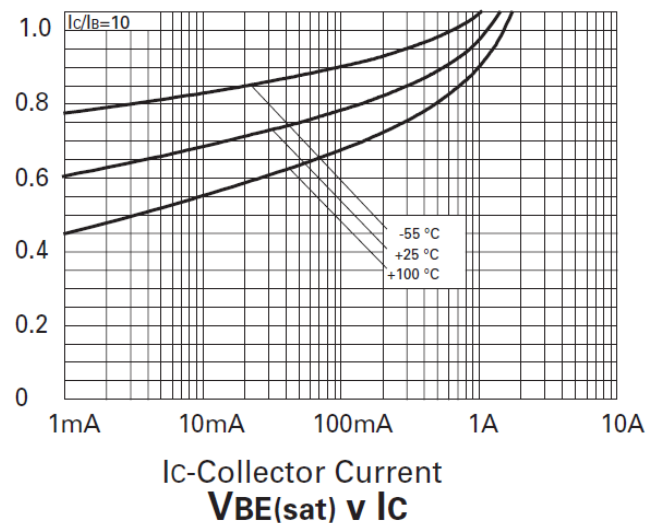
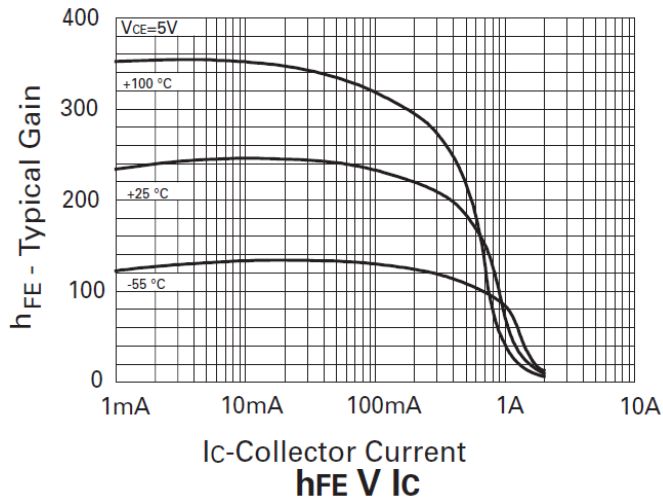
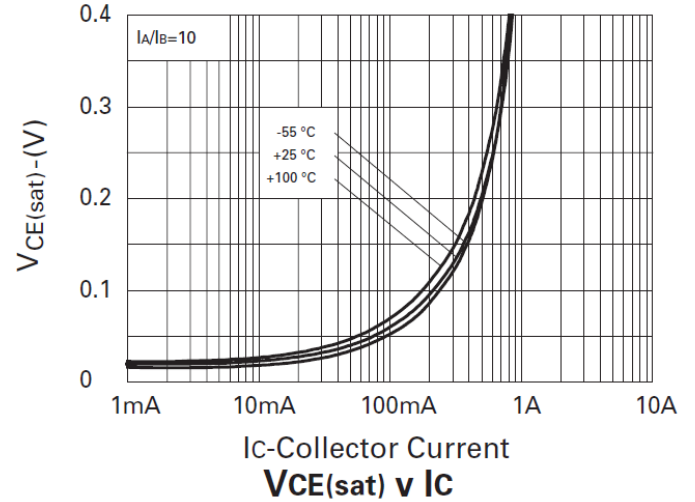
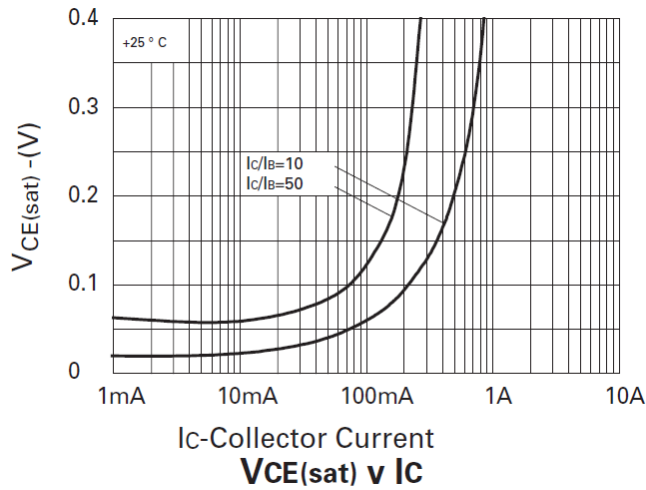


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-120	—	—	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 11)	BV _{CEO}	-100	—	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	—	—	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	—	—	-100	nA	V _{CB} = -100V
Emitter Cutoff Current	I _{EBO}	—	—	-100	nA	V _{EB} = -5V
Emitter Cutoff Current	I _{CES}	—	—	-100	nA	V _{CES} = -100V
DC current transfer Static ratio (Note 11)	h _{FE}	100 100 100 50	—	— — 300 —	—	I _C = -1mA, V _{CE} = -5V I _C = -250mA, V _{CE} = -5V I _C = -500mA, V _{CE} = -5V I _C = -1A, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note 11)	V _{CE(sat)}	—	—	-0.2 -0.3	V	I _C = -250mA, I _B = -25mA I _C = -500mA, I _B = -50mA
Base-Emitter Saturation Voltage (Note 11)	V _{BE(sat)}	—	—	-1.1	V	I _C = -500mA, I _B = -50mA
Base-Emitter Turn-on Voltage (Note 11)	V _{BE(on)}	—	—	-1.0	V	I _C = -1mA, V _{CE} = -5V
Transitional Frequency	f _T	50	—	—	MHz	I _E = -50mA, V _{CE} = -10V f = 100MHz
Output capacitance	C _{obo}	—	—	5	pF	V _{CB} = -10V, f = 1MHz,

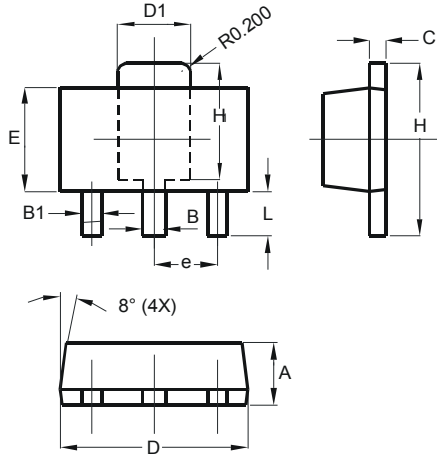
Note: 11. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

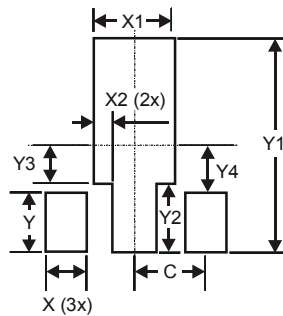
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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